

MOTOROLA
Semiconductors
 BOX 955 • PHOENIX, ARIZONA 85001

2N5209
2N5210

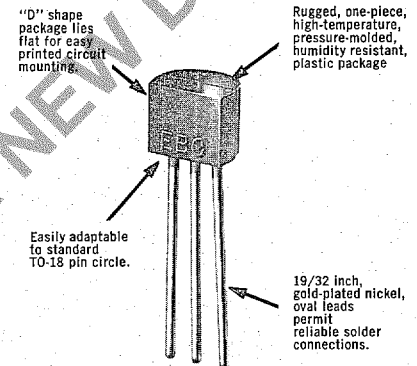
**NPN SILICON
 AMPLIFIER TRANSISTORS**

MARCH 1968 — DS 5241

NPN SILICON ANNULAR* TRANSISTORS

... NPN silicon annular transistors designed for low-level, low-noise amplifier applications and for complementary circuitry with PNP types 2N5086 and 2N5087.

- ⊙ High Breakdown Voltage — $BV_{CEO} = 50 \text{ Vdc (Min) @ } I_C = 1.0 \text{ mA}$
- ⊙ Low Noise Figure — @ $f = 1.0 \text{ kHz}$
 2N5209 — $NF = 4.0 \text{ dB (Max)}$
 2N5210 — $NF = 3.0 \text{ dB (Max)}$
- ⊙ High DC Current Gain at Low Current —
 2N5210 — $h_{FE} = 200 @ I_C = 100 \mu\text{A}$
- ⊙ Low Current-Gain — Bandwidth Product to Facilitate Audio Frequency Design — $f_T = 80 \text{ MHz (Typ)}$
- ⊙ Low Leakage Current — $I_{CBO} = 10 \text{ nA max @ } V_{CB} = 10 \text{ V}$
- ⊙ Low Collector Base Capacitance — $C_{cb} = 4.0 \text{ pF (Max)}$



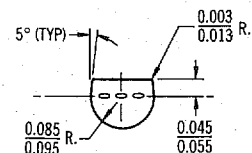
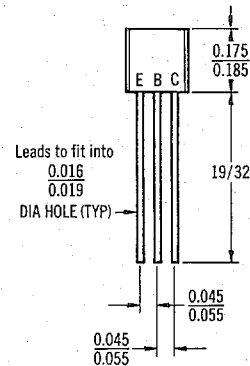
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CEO}	50	Vdc
Collector-Base Voltage	V_{CB}	50	Vdc
Emitter-Base Voltage	V_{EB}	4.5	Vdc
Collector Current — Continuous	I_C	50	mAdc
Peak		100	
Total Device Dissipation @ $T_A = 25^\circ\text{C}$	P_D	310	mW
Derate above 25°C		2.81	mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-55 to +135	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient	θ_{JA}	0.357	$^\circ\text{C/mW}$

* Annular Semiconductors Patented by Motorola Inc.



TO-92
 CASE 29(1)

SI HIGH-FREQUENCY TRANSISTOR
 2N5209, 2N5210
 DS 5241



2N5209, 2N5210

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Collector-Emitter Breakdown Voltage ($I_C = 1.0 \text{ mA}$, $I_B = 0$)	BV_{CEO}	50	-	-	Vdc
Collector-Base Breakdown Voltage ($I_C = 0.1 \text{ mA}$, $I_E = 0$)	BV_{CBO}	50	-	-	Vdc
Collector Cutoff Current ($V_{CB} = 10 \text{ Vdc}$, $I_E = 0$) ($V_{CB} = 35 \text{ Vdc}$, $I_E = 0$)	I_{CBO}	-	-	10 50	nAdc
Emitter Cutoff Current ($V_{BE} = 3.0 \text{ Vdc}$, $I_C = 0$) ($V_{BE} = 4.5 \text{ Vdc}$, $I_C = 0$)	I_{EBO}	-	-	50 100	nAdc

ON CHARACTERISTICS

DC Current Gain ($I_C = 100 \mu\text{Adc}$, $V_{CE} = 5.0 \text{ Vdc}$)	h_{FE}	2N5209	100	-	300	-
		2N5210	200	-	600	-
($I_C = 1.0 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$)		2N5209	150	-	-	-
		2N5210	250	-	-	-
($I_C = 10 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$)	2N5209	150	-	-	-	
	2N5210	250	-	-	-	
Collector-Emitter Saturation Voltage ($I_C = 10 \text{ mA}$, $I_B = 1.0 \text{ mA}$)	$V_{CE(sat)}$	-	-	0.7	Vdc	
Base-Emitter On Voltage ($I_C = 1.0 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$)	$V_{BE(on)}$	-	-	0.85	Vdc	

SMALL-SIGNAL CHARACTERISTICS

Current-Gain-Bandwidth Product ($I_C = 500 \mu\text{Adc}$, $V_{CE} = 5.0 \text{ Vdc}$, $f = 20 \text{ MHz}$)	f_T	30	80	-	MHz	
Collector Base Capacitance ($V_{CB} = 5.0 \text{ Vdc}$, $I_E = 0$, $f = 100 \text{ kHz}$) (emitter guarded)	C_{cb}	-	-	4.0	pF	
Small-Signal Current Gain ($I_C = 1.0 \text{ mA}$, $V_{CE} = 5.0 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)	h_{fe}	2N5209	150	-	600	-
		2N5210	250	-	900	-
Noise Figure ($I_C = 20 \mu\text{Adc}$, $V_{CE} = 5.0 \text{ Vdc}$, $R_S = 22 \text{ k ohms}$, $f = 10 \text{ Hz to } 15.7 \text{ kHz}$)	NF	2N5209	-	-	3.0	dB
		2N5210	-	-	2.0	
($I_C = 20 \mu\text{Adc}$, $V_{CE} = 5.0 \text{ Vdc}$, $R_S = 10 \text{ k ohms}$, $f = 1.0 \text{ kHz}$)		2N5209	-	1.6	4.0	
		2N5210	-	1.4	3.0	

NOISE FIGURE ($V_{CE} = 5.0 \text{ Vdc}$, $T_A = 25^\circ\text{C}$)

FIGURE 1 — NOISE FIGURE versus FREQUENCY

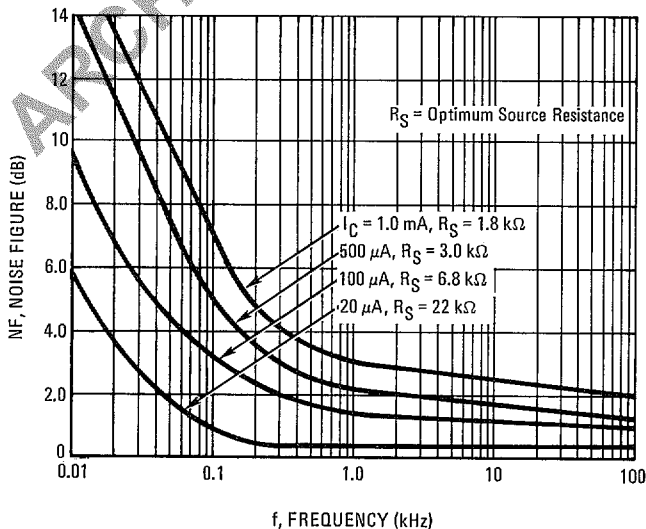
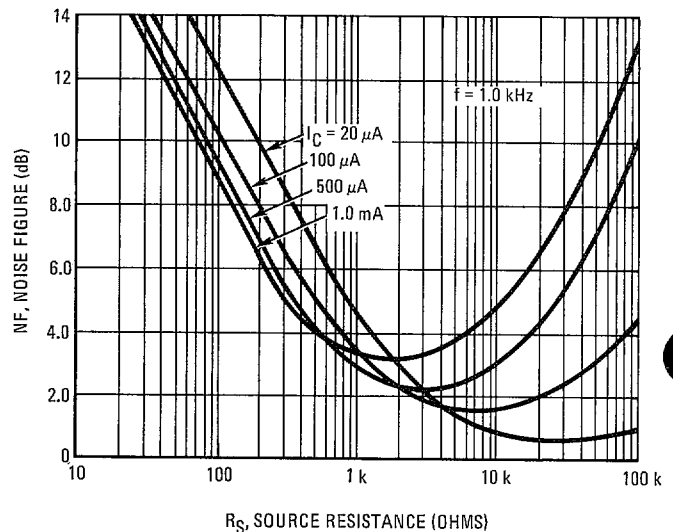


FIGURE 2 — NOISE FIGURE versus SOURCE RESISTANCE



h PARAMETERS

$V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$, $T_A = 25^\circ \text{ C}$
(For Figures 3, 4, 5, 6, 8)

This group of graphs illustrates the relationship of the "h" parameters for this series of transistors. To obtain these curves, 4 units were selected and identified by number — the same units were used to develop curves on each graph.

FIGURE 3 – INPUT IMPEDANCE versus COLLECTOR CURRENT

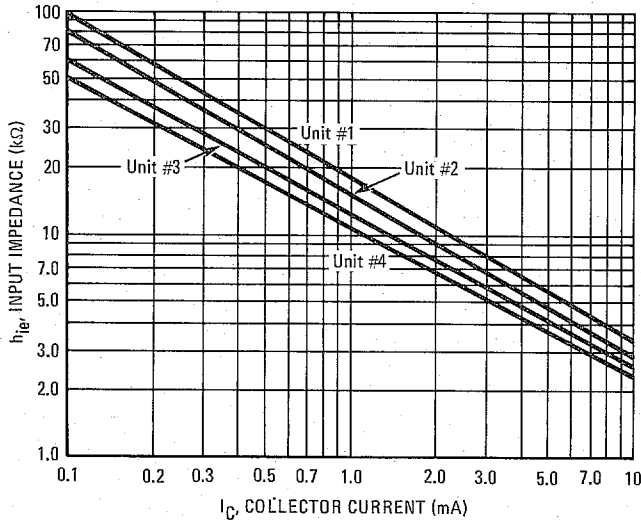


FIGURE 4 – VOLTAGE FEEDBACK RATIO versus COLLECTOR CURRENT

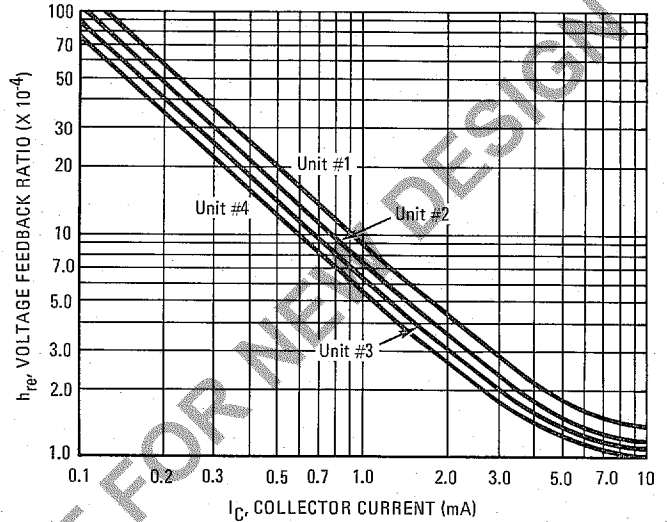


FIGURE 5 – CURRENT GAIN versus COLLECTOR CURRENT

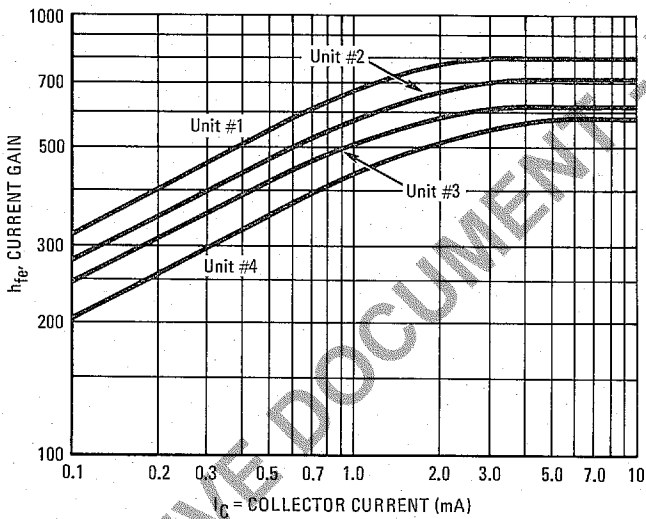


FIGURE 6 – OUTPUT ADMITTANCE versus COLLECTOR CURRENT

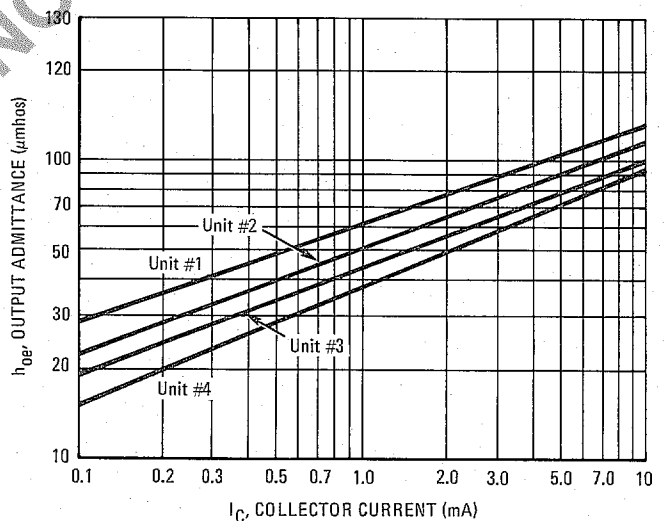


FIGURE 7 – EFFECT OF VOLTAGE

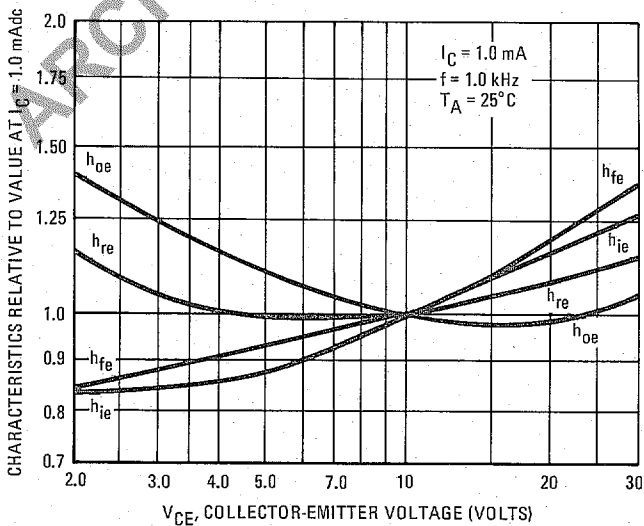


FIGURE 8 – HYBRID DETERMINANT versus COLLECTOR CURRENT

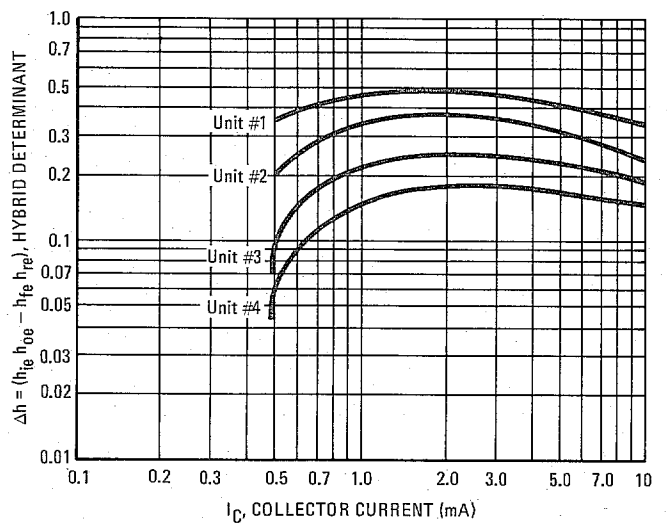


FIGURE 9 – DC CURRENT GAIN

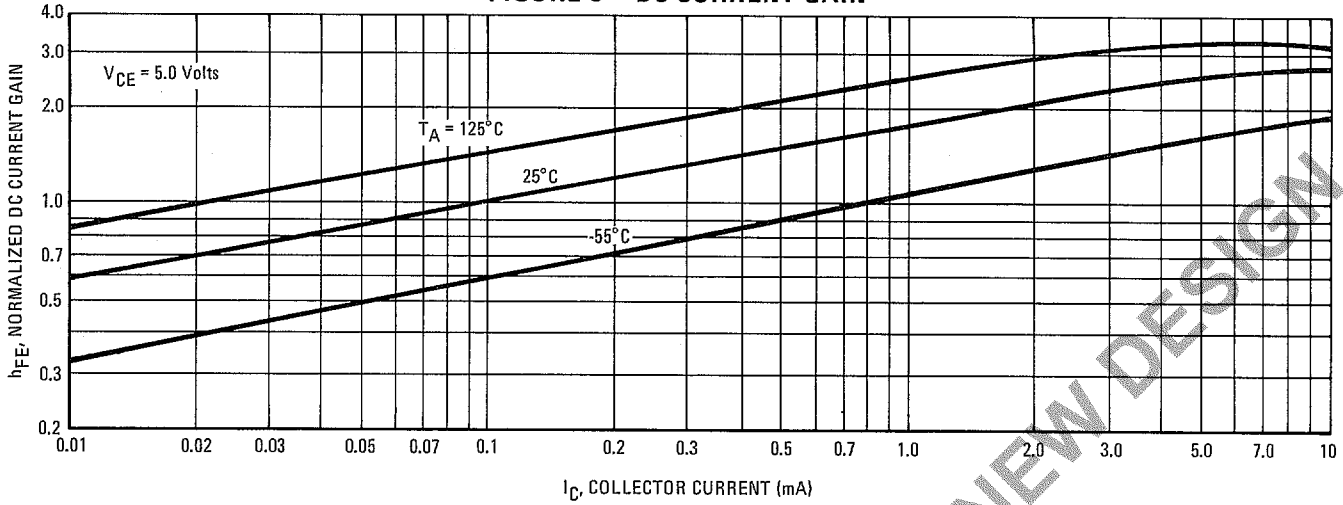


FIGURE 10 – COLLECTOR SATURATION REGION

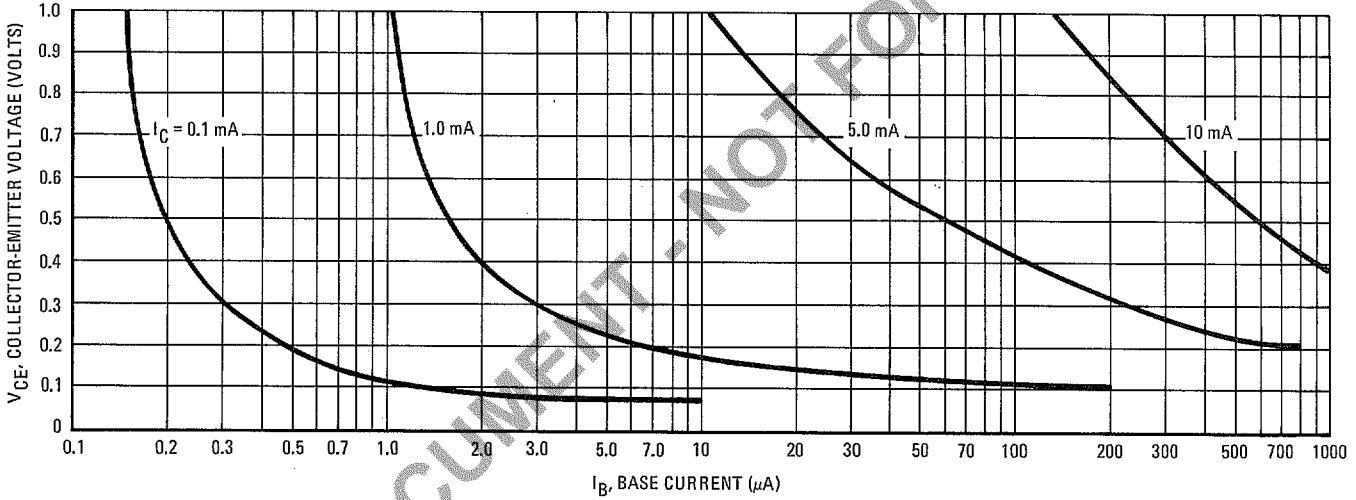


FIGURE 11 – CURRENT-GAIN – BANDWIDTH PRODUCT

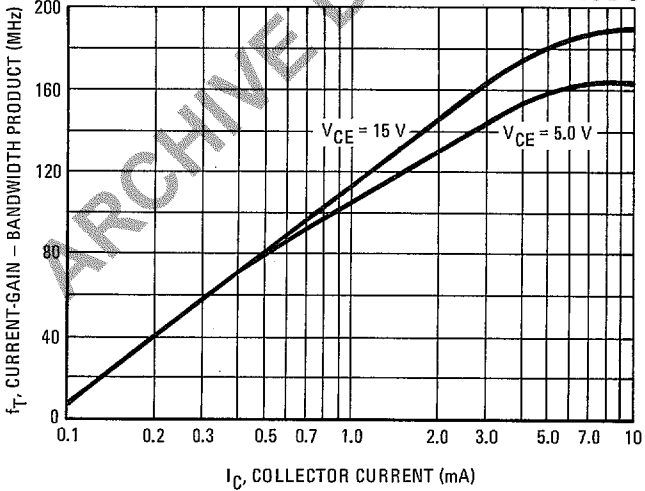
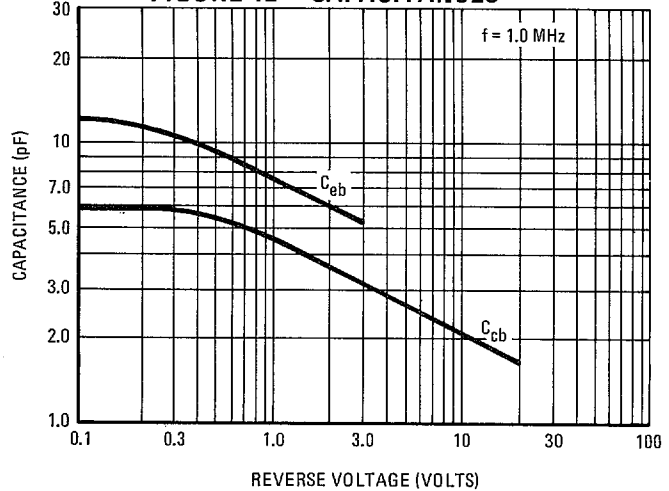


FIGURE 12 – CAPACITANCES



MOTOROLA Semiconductor Products Inc.

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